



June 26, 2012

PCN Number: 1206

PCN Change Level: Major

Subject: Addition of ASE (Malaysia) for Electrical Test, Mark and EOL

Dear Customer,

The purpose of this PCN is to notify all customers that Microsemi SoC products group (formerly Actel) will be adding the services of ASE (Malaysia) for Electrical Test (Wafer and Package Test), Mark and End-of Line processing (lead scan, bake, and dry-pack) for all commercial, industrial and automotive grade products (except all hermetic packages: CQ, PG, CG, LG, etc.).

Microsemi SoC products could be tested at Microsemi SoC (San Jose), Ardentec (Taiwan), UTAC (China), Amkor (Philippines) or ASE (Malaysia) qualified locations to allow supply continuity, as needed.

There is no change to form, fit, function, test coverage, or quality of the product. The tester platforms at ASE (Malaysia) are correlated to Microsemi SoC (San Jose). All test locations have the same tester platform and test programs as Microsemi SoC (San Jose).

This PCN is not applicable to all ITAR-controlled products, M-Temp products, B-Flow products, RT products and Automotive Grade products with PPAP; these will remain in Microsemi SoC (San Jose) for all processing.

Microsemi SoC will begin using ASE (Malaysia) as an additional test source beginning Oct 2012. See the implementation schedule and affected part number list for details.

For any questions, contact Microsemi's Application Technical Support at soc_tech@microsemi.com.

Regards,

Microsemi Corporation

[Addendum A: ASE \(Malaysia\) Overview Report](#)

[Addendum B: Implementation \(WS and FT Correlation\) Schedule](#)

[Addendum C: Affected Part Number List](#)